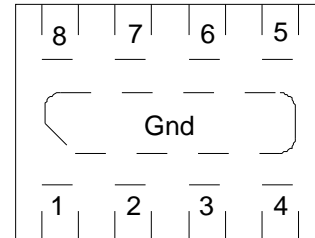


## PROTECTION PRODUCTS

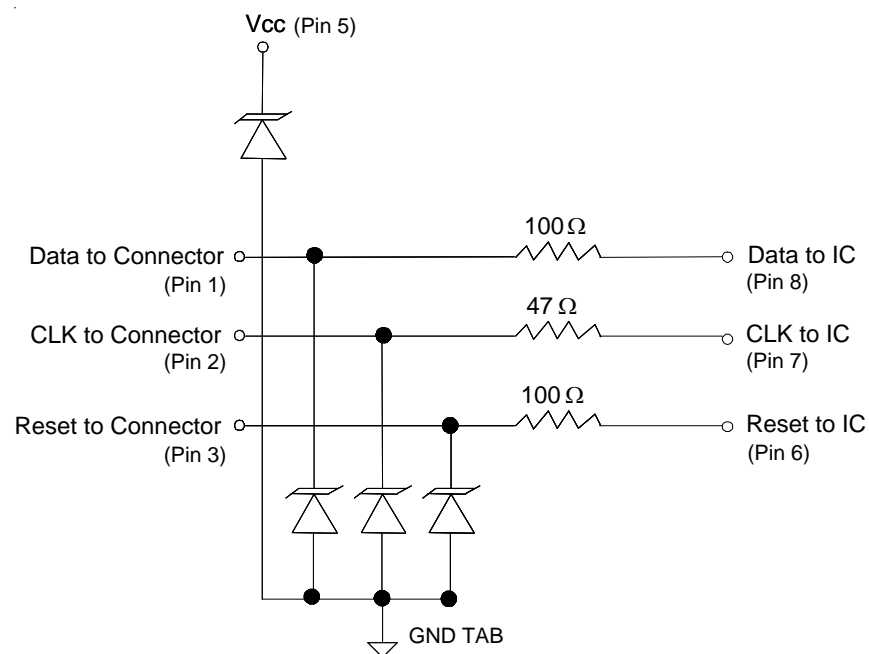
### Pin Identification and Configuration

Pin	Symbol	Identification
1	Data	Data Input (SIM Connector Side)
2	CLK	Clock Input (SIM Connector Side)
3	Reset	Reset Input (SIM Connector Side)
4	NC	No Connect
5	Vcc	Power Supply ESD Protection (SIM Connector Side)
6	Reset	Reset Output (IC Side)
7	CLK	Clock input (IC Side)
8	Data	Data Output (IC Side)
Center tab	GND	Ground connection



**Pin Configuration (Top View)**

### Schematics & Component Values



## PROTECTION PRODUCTS

### Maximum Ratings

Rating	Symbol	Value	Units
ESD per IEC 61000-4-2 (Air) <sup>1</sup> ESD per IEC 61000-4-2 (Contact)	$V_{ESD}$	+/- 18 +/- 10	kV
Junction Temperature	$T_J$	125	°C
Operating Temperature	$T_{op}$	-40 to +85	°C
Storage Temperature	$T_{STG}$	-55 to +150	°C

### Electrical Characteristics (T=25°C)

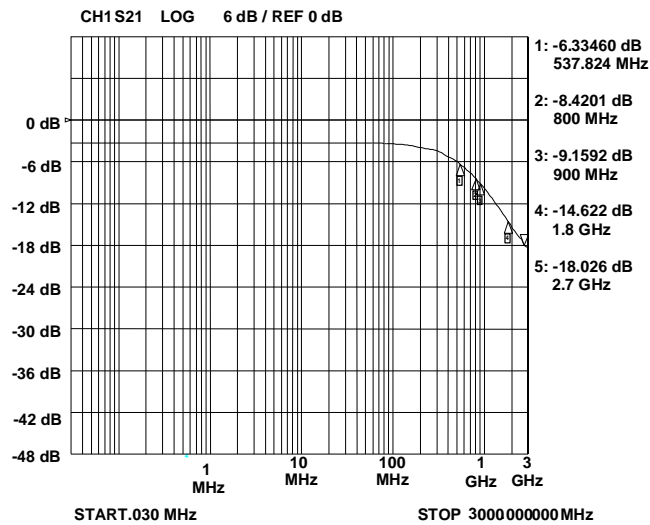
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
TVS Reverse Stand-Off Voltage	$V_{RWM}$				5	V
TVS Reverse Breakdown Voltage	$V_{BR}$	$I_t = 1mA$	6	8	10	V
TVS Reverse Leakage Current	$I_R$	$V_{RWM} = 5.0V$			0.5	μA
Reset Series Resistors	$R_{RST}$	Each Line	85	100	115	Ohms
Clk Series Resistors	$R_{CLK}$	Each Line	40	47	55	Ohms
Data Series Resistors	$R_{DATA}$	Each Line	85	100	115	Ohms
Total Capacitance	$C_{in}$	Input to Gnd, Each Line $V_R = 0V, f = 1MHz$	8	10	12	pF

Note: 1) ESD input at Pins 1, 2, 3, 5

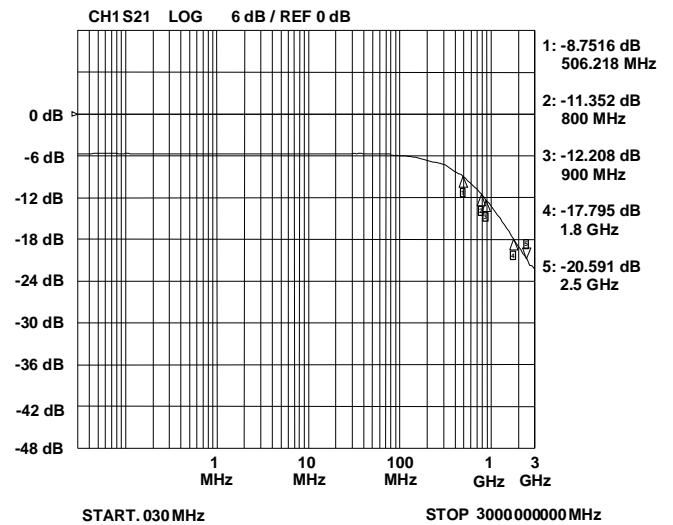
## PROTECTION PRODUCTS

### Typical Characteristics

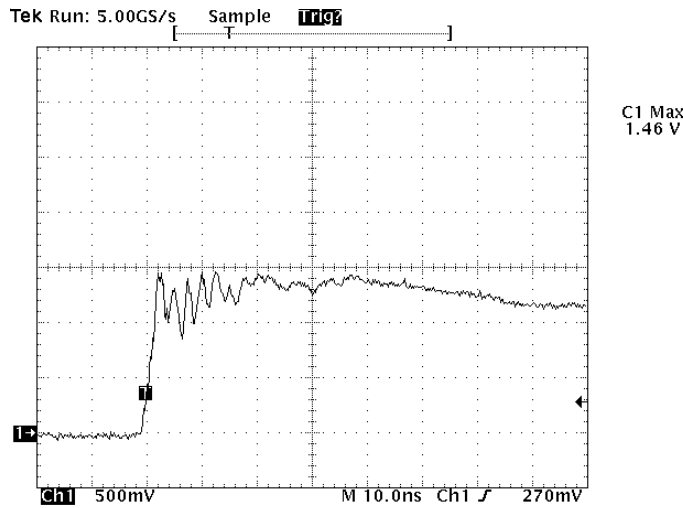
Typical Insertion Loss S21 (Pin 2 to 7)



Typical Insertion Loss S21 (Pin 1 to 8 and Pin 3 to 6)

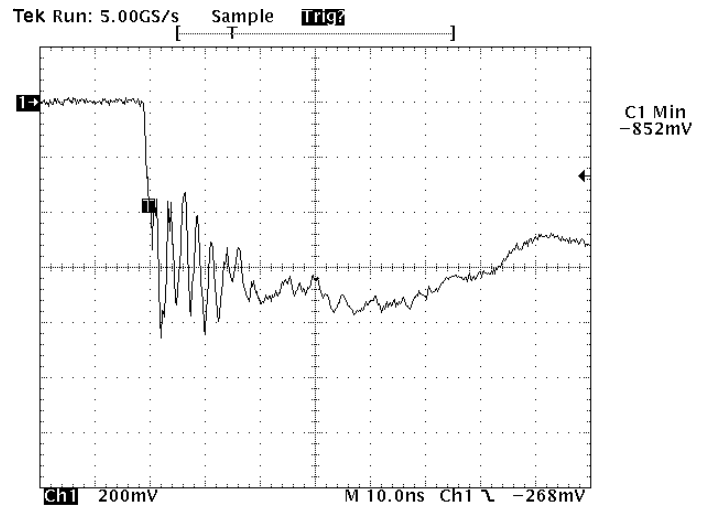


ESD Clamping (+8kV Contact)



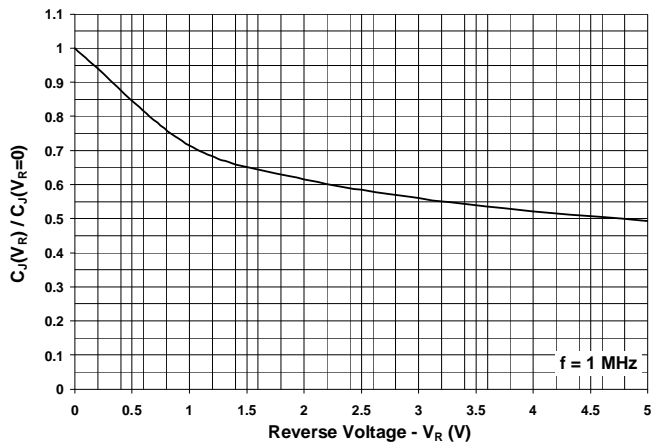
Note: Data is taken with a 10x attenuator

ESD Clamping (-8kV Contact)



Note: Data is taken with a 10x attenuator

Normalized Capacitance vs. Reverse Voltage

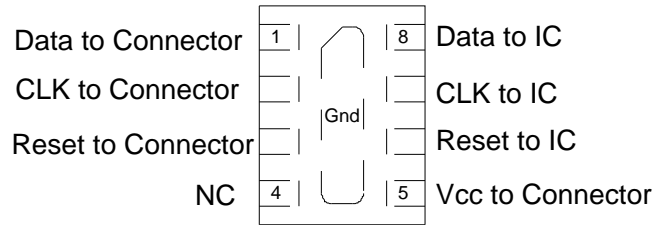


## PROTECTION PRODUCTS

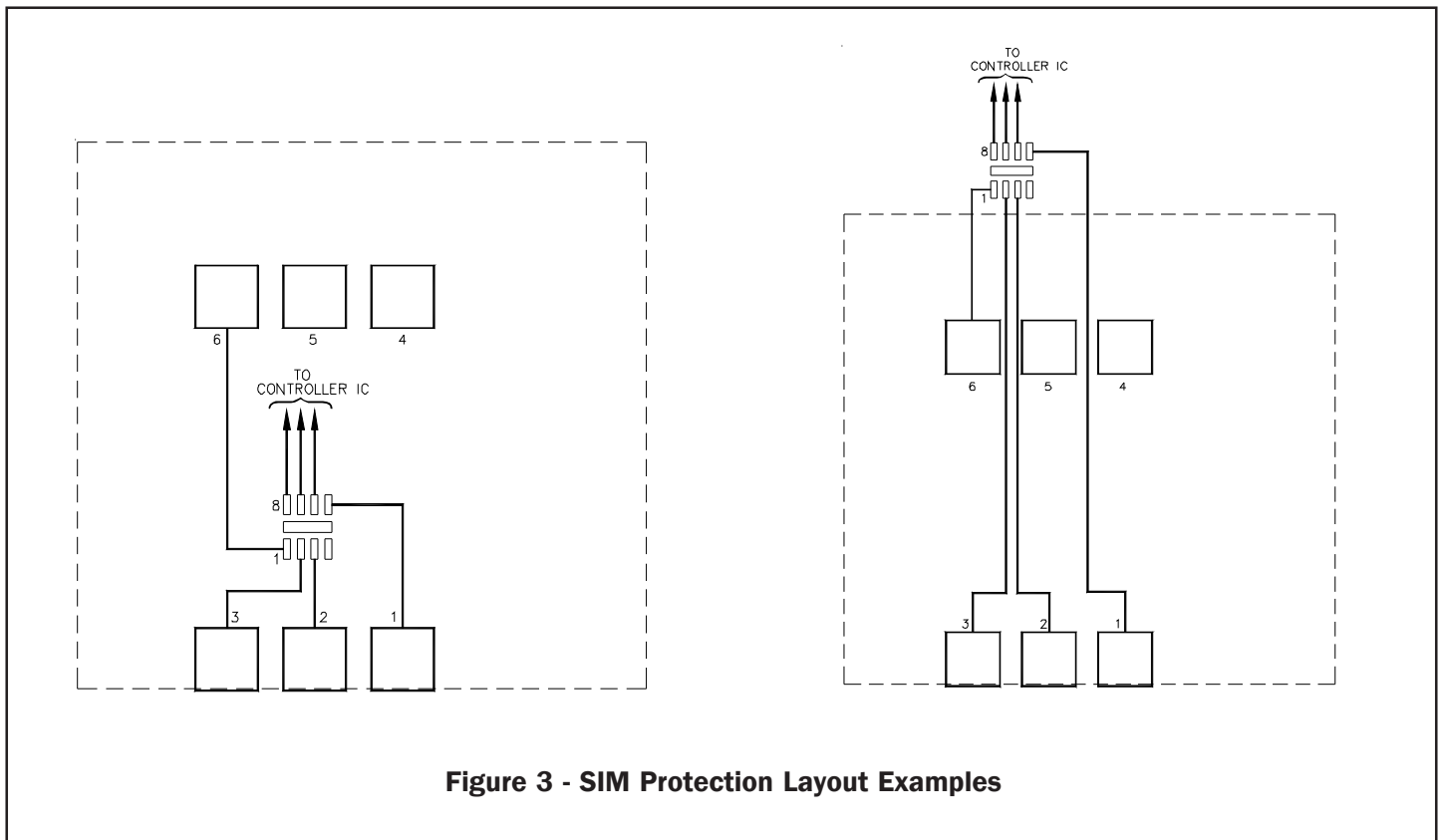
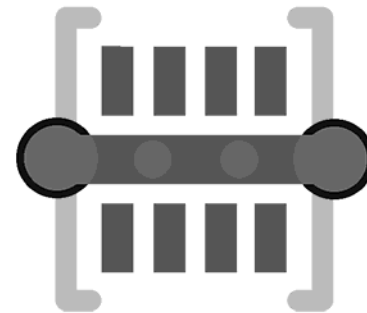
### Device Connection

The EClamp2465T designed with ease of layout in mind. The package has flow through design which allows the designer to route the signals straight in and out between the SIM port connector and the SIM controller. The device is in a 8-pin SLP package. Electrical connection is made to the 8 pins located at the bottom of the device. A center tab serves as the ground connection. Pin connections are noted in Figure 1. Note that the ESD protection diodes are located at pins 1 - 3 for the data and clock lines. This means the device is directional. Therefore, Pins 1 - 3 must be routed to the SIM connector while pins 6 - 8 are routed to the protected IC. Pin 5 is routed to the Vcc pin of the SIM connector. Typical layout examples are shown in Figure 3. All path lengths should be kept as short as possible to minimize the effects of parasitic inductance in the board traces. The center tab should be connected directly to the ground plane. Multiple micro-vias are recommended in the device ground pad as shown in Figure 2. Multiple vias in the device ground pad will result in a lower inductive ground loop, increasing the ESD effectiveness of the device.

**Figure 1 - Pin Identification and Configuration (Top Side View)**



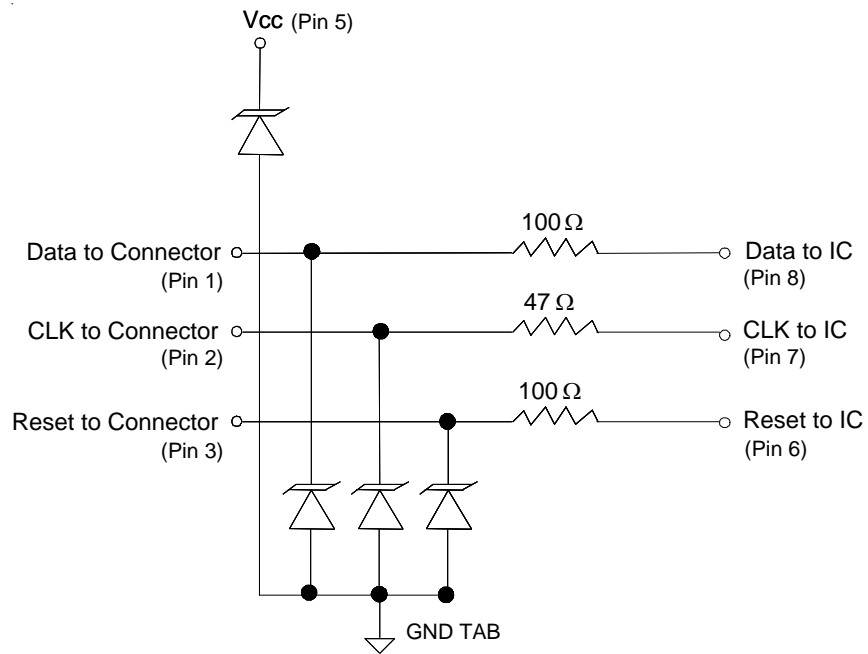
**Figure 2 - Recommended Layout Using Ground Vias**



**Figure 3 - SIM Protection Layout Examples**

## PROTECTION PRODUCTS

### Applications Information - Spice Model



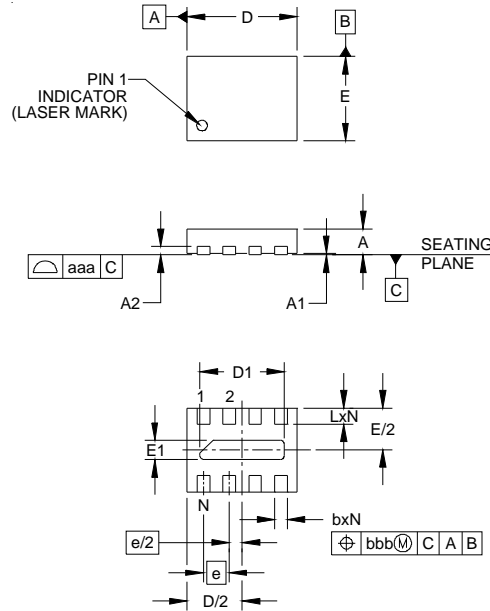
**EClamp2465T Spice Model**

Note: All TVS shown in the circuit use D1 Parameters

Table 1 - EClamp2465T Spice Parameters		
Parameter	Unit	D1 (TVS)
IS	Amp	2E-15
BV	Volt	7.5
VJ	Volt	0.775
RS	Ohm	1.05
IBV	Amp	1E-3
CJO	Farad	9E-12
TT	sec	2.541E-9
M	--	0.246
N	--	1.1
EG	eV	1.11

## PROTECTION PRODUCTS

### Outline Drawing - SLP1713P8T

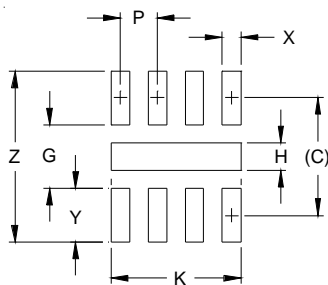


DIM	DIMENSIONS					
	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	.015	.016	.017	0.37	0.40	0.43
A1	.000	.001	.002	0.00	0.02	0.05
A2		(.005)			(0.13)	
b	.006	.008	.010	0.15	0.20	0.25
D	.065	.067	.070	1.65	1.70	1.78
D1	.047	.051	.055	1.20	1.30	1.40
E	.049	.051	.054	1.25	1.30	1.38
E1	.008	.012	.016	0.20	0.30	0.40
e	.016 BSC			0.40 BSC		
L	.008	.010	.012	0.20	0.25	0.30
N	8			8		
aaa	.003			0.08		
bbb	.004			0.10		

**NOTES:**

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

### Land Pattern - SLP1713P8T



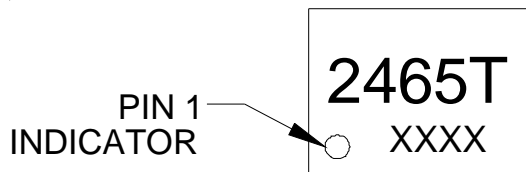
DIM	DIMENSIONS	
	INCHES	MILLIMETERS
C	(.050)	(1.27)
G	.027	0.69
H	.012	0.30
K	.055	1.40
P	.016	0.40
X	.008	0.20
Y	.023	0.58
Z	.073	1.85

**NOTES:**

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.
3. THERMAL VIAS IN THE LAND PATTERN OF THE EXPOSED PAD SHALL BE CONNECTED TO A SYSTEM GROUND PLANE. FAILURE TO DO SO MAY COMPROMISE THE THERMAL AND/OR FUNCTIONAL PERFORMANCE OF THE DEVICE.

## PROTECTION PRODUCTS

### Marking



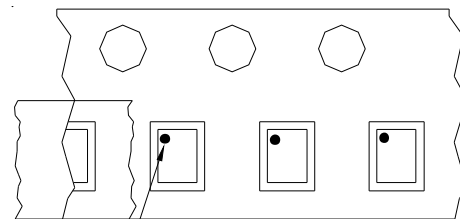
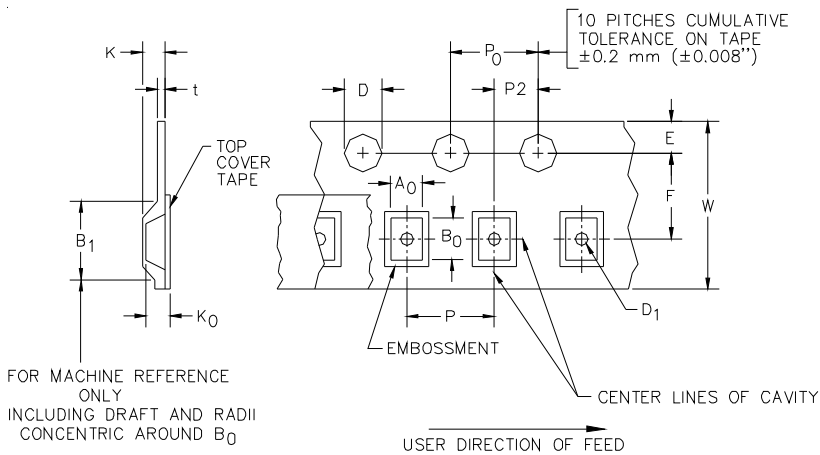
### Ordering Information

Part Number	Qty per Reel	Reel Size
EClamp2465T.TCT	3000	7 Inch

This is a lead-free RoHS/WEEE Compliant Device  
EMIClamp and EClamp are marks of Semtech Corporation

XXXX = Date Code

### Tape and Reel Specification



Pin 1 Location

→ User Direction of feed

### Device Orientation in Tape

A0	B0	K0
1.51 +/-0.10 mm	1.91 +/-0.10 mm	0.66 +/-0.10 mm

Tape Width	B, (Max)	D	D1	E	F	K (MAX)	P	P0	P2	T(MAX)	W
8 mm	4.2 mm (.165)	1.5 + 0.1 mm - 0.0 mm (0.59 +.005 - .000)	0.8 mm ±0.05 (.031)	1.750±.10 mm (.069±.004)	3.5±0.05 mm (.138±.002)	2.4 mm (.094)	4.0±0.1 mm (.157±.00-4)	4.0±0.1 mm (.157±.00-4)	2.0±0.05mm (.079±.002)	0.4 mm (.016)	8.0 mm + 0.3 mm - 0.1 mm (.312±.012)

### Contact Information

Semtech Corporation  
Protection Products Division  
200 Flynn Rd., Camarillo, CA 93012  
Phone: (805)498-2111 FAX (805)498-3804

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